

Title (en)

Master slice type integrated circuit device and manufacturing method thereof.

Title (de)

Integriertes Schaltkreis-Bauelement vom Typ "Master Slice" und dessen Herstellungsverfahren.

Title (fr)

Dispositif de circuit intégré et son procédé de fabrication.

Publication

**EP 0314376 A1 19890503 (EN)**

Application

**EP 88309787 A 19881019**

Priority

- JP 14515688 A 19880613
- JP 26706587 A 19871022
- JP 26706687 A 19871022
- JP 26706787 A 19871022
- JP 27621487 A 19871030

Abstract (en)

This invention is to realize a final circuit by wiring only the top layer depending on the individual circuits, by fabricating a master slice in the step of up to forming plural semiconductor elements such as transistors on a semiconductor substrate, forming a lower layer of versatile wiring pieces thereon, and forming contact holes thereon. In this way, since the step just before formation of the top layer wiring can be carried out regardless of the features of individual circuits, preliminary mass productions are possible, and final products can be completed only by forming the wiring of the top layer depending on the requirements of the users. Accordingly, it is applicable to a wide variety of products, and the term for development and manufacture can be tremendously shortened.

IPC 1-7

**H01L 23/52**

IPC 8 full level

**H01L 23/522** (2006.01); **H01L 23/528** (2006.01)

CPC (source: EP KR)

**H01L 21/02** (2013.01 - KR); **H01L 21/82** (2013.01 - KR); **H01L 23/5226** (2013.01 - EP); **H01L 23/528** (2013.01 - EP);  
**H01L 2924/0002** (2013.01 - EP)

Citation (search report)

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- [A] EP 0210397 A1 19870204 - IBM [US]
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US5399517A; EP0650196A3; EP0338817A3; US5506162A; DE4128568A1; US5196362A; DE4128568C2

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KR 930000602 B1 19930125

DOCDB simple family (application)

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